Materials Declaration

Package	TSSOP - EP
Body Size	4.4
LeadCount	16
Option	Pb-free, Halide-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	86.9	9.60 E-03	150421
Epoxy & Phenol Resin	12.8	1.41 E-03	22119
Carbon black	0.3	3.42 E-05	537
Subtotal		1.10 E-02	173077

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	3.52 E-02	552126
Ni	3	1.10 E-03	17218
Si	0.65	2.38 E-04	3731
Mg	0.15	5.49 E-05	861
Subtotal		3.66 E-02	573936

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	5.00 E-04	7837

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	1.51 E-03	23647

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	3.13 E-04	4908

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.36 E-02	212850

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag	73.40	1.75 E-04	2748
Epoxy Resin	18.35	4.38 E-05	687
Metal oxide	2.75	6.57 E-06	103
Curing and hardening agent	2.75	6.57 E-06	103
Gamma Butyrolactone	2.75	6.57 E-06	103
		2.39 E-04	3744

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA3050B. ICP-AES.
Cd	Not Detected	EPA3050B. ICP-AES.
Hg	Not Detected	EPA 3052B. Mercury Analyser
Cr+6	Not Detected	EPA 7196A. UV-VIS.
PBB	Not Detected	EPA 1614. GC-MS.
PBDE	Not Detected	EPA 1614. GC-MS.

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	Draft IEC 62321. ICP-OES.
Cd	Not Detected	Draft IEC 62321. ICP-OES.
Hg	Not Detected	Draft IEC 62321. ICP-OES.
Cr+6	Not Detected	Draft IEC 62321. UV-VIS.
PBB	Not Detected	Draft IEC 62321. GC-MSD.
PBDE	Not Detected	Draft IEC 62321. GC-MSD.

Package Totals

Weight (g)	PPM
6.38 E-02	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ADI Proprietary

Materials Declaration

Package	TSSOP-EP
Body Size	4.4
LeadCount	16
Option	with Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	82	9.05 E-03	141923
Resin	16	1.77 E-03	27692
Sb2O3	1.4	1.55 E-04	2423
Brominated Resin	0.6	6.62 E-05	1038
Subtotal		1.10 E-02	173077

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	3.52 E-02	552126
Ni	3	1.10 E-03	17218
Si	0.65	2.38 E-04	3731
Mg	0.15	5.49 E-05	861
Subtotal		3.66 E-02	573936

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	5.00 E-04	7837

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	1.28 E-03	20100
Pb	15	2.26 E-04	3547
Subtotal		1.51 E-03	23647

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	3.13 E-04	4908

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.36 E-02	212850

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag	75.47	1.80 E-04	2826
Epoxy resin	18.87	4.51 E-05	707
Gamma Butyrolactone	2.83	6.76 E-06	106
Curing agent & hardener	2.83	6.76 E-06	106
Subtotal		2.39 E-04	3744

Package Totals

Weight (g)	PPM
6.38 E-02	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	Draft IEC 62321. ICP-OES.
Cd	Not Detected	Draft IEC 62321. ICP-OES.
Hg	Not Detected	Draft IEC 62321. ICP-OES.
Cr+6	Not Detected	Draft IEC 62321. UV-VIS.
PBB	Not Detected	Draft IEC 62321. GC-MSD.
PBDE	Not Detected	Draft IEC 62321. GC-MSD.

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	Draft IEC 62321. ICP-OES.
Cd	Not Detected	Draft IEC 62321. ICP-OES.
Hg	Not Detected	Draft IEC 62321. ICP-OES.
Cr+6	Not Detected	Draft IEC 62321. UV-VIS.
PBB	Not Detected	Draft IEC 62321. GC-MSD.
PBDE	Not Detected	Draft IEC 62321. GC-MSD.

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